

**PATENT ASSIGNMENT**

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Robert C. Pack	03/16/2011
William Wai Yan Ho	03/16/2011
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<b>Postal Code:</b>	95037
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	13047621
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<b>Total Attachments: 1</b> source=20110317_007_assign#page1.tif	

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## ASSIGNMENT OF PATENT APPLICATION

WHEREAS, **Robert C. Pack**, residing at 16813 Sorrel Way, Morgan Hill, California 94404 and **William Wai Yan Ho**, residing at 1079 Prouty Way, San Jose, California 95129, hereinafter referred to as "Assignors," are the inventors of the invention described and set forth in the below-identified application for United States Letters Patent:

Title of Invention:       **Modeling and Simulating the Impact of Imperfectly Patterned Via Arrays on Integrated Circuits**

Filing Date:               March 14, 2011

Application No.:         13/047,621

WHEREAS, **Grid Simulation Technology, Inc.**, having a place of business at 1295 E. Dunne Avenue, Suite 215, Morgan Hill, California 95037, hereinafter referred to as "Assignee," is desirous of acquiring an interest in the invention and application and in any U.S. Letters Patent and Registrations which may be granted on the same.

For good and valuable consideration, receipt of which is hereby acknowledged by Assignors, Assignors have assigned, and by these presents do assign to Assignee all right, title, and interest in and to the invention and application and to all foreign counterparts (including patent, utility model, and industrial designs), and in and to any Letters Patent and Registrations which may hereafter be granted on the same in the United States and all countries throughout the world, and to claim the priority from the application as provided by the Paris Convention. The right, title, and interest is to be held and enjoyed by Assignee and Assignee's successors and assigns as fully and exclusively as it would have been held and enjoyed by Assignor had this Assignment not been made, for the full term of any Letters Patent and Registrations which may be granted thereon, or of any provisional, nonprovisional, division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation, or extension thereof.

Assignors further agree that they will, without charge to Assignee, but at Assignee's expense, (a) cooperate with Assignee in the prosecution of U.S. patent applications and foreign counterparts on the invention and any improvements, (b) execute, verify, acknowledge, and deliver all such further papers, including patent applications and instruments of transfer, and (c) perform such other acts as Assignee lawfully may request to obtain or maintain Letters Patent and Registrations for the invention and improvements in any and all countries, and to vest title thereto in Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignors have signed their names on the date indicated.

/ Robert C. Pack /

3/16/2011

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**Robert C. Pack**

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Date

/ William Wai Yan Ho /

3/16/2011

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**William Wai Yan Ho**

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Date